

FIG. 1 B

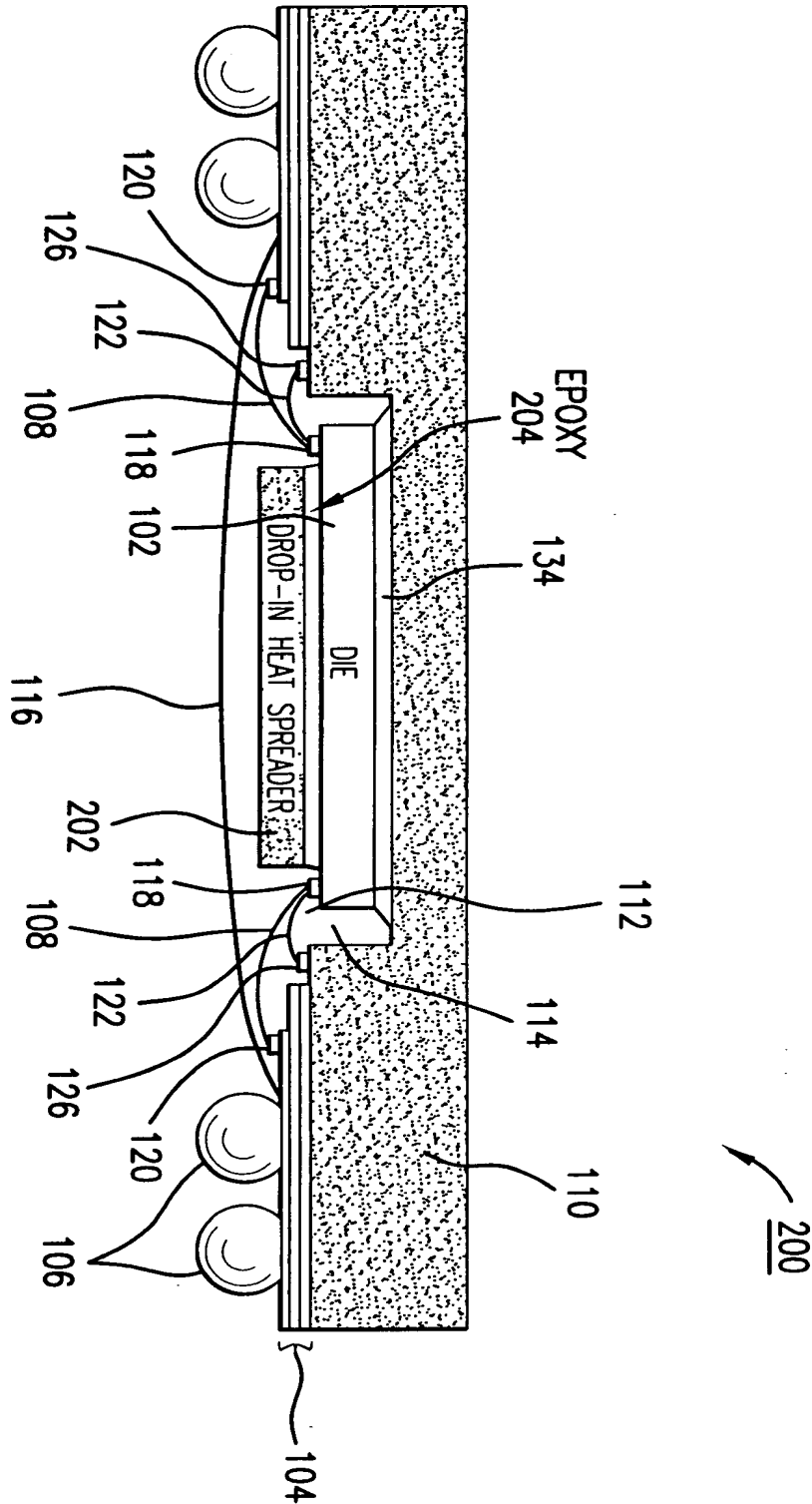


FIG. 2A

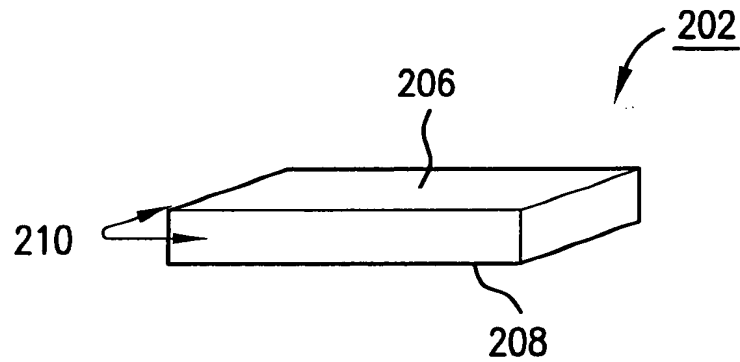


FIG. 2B

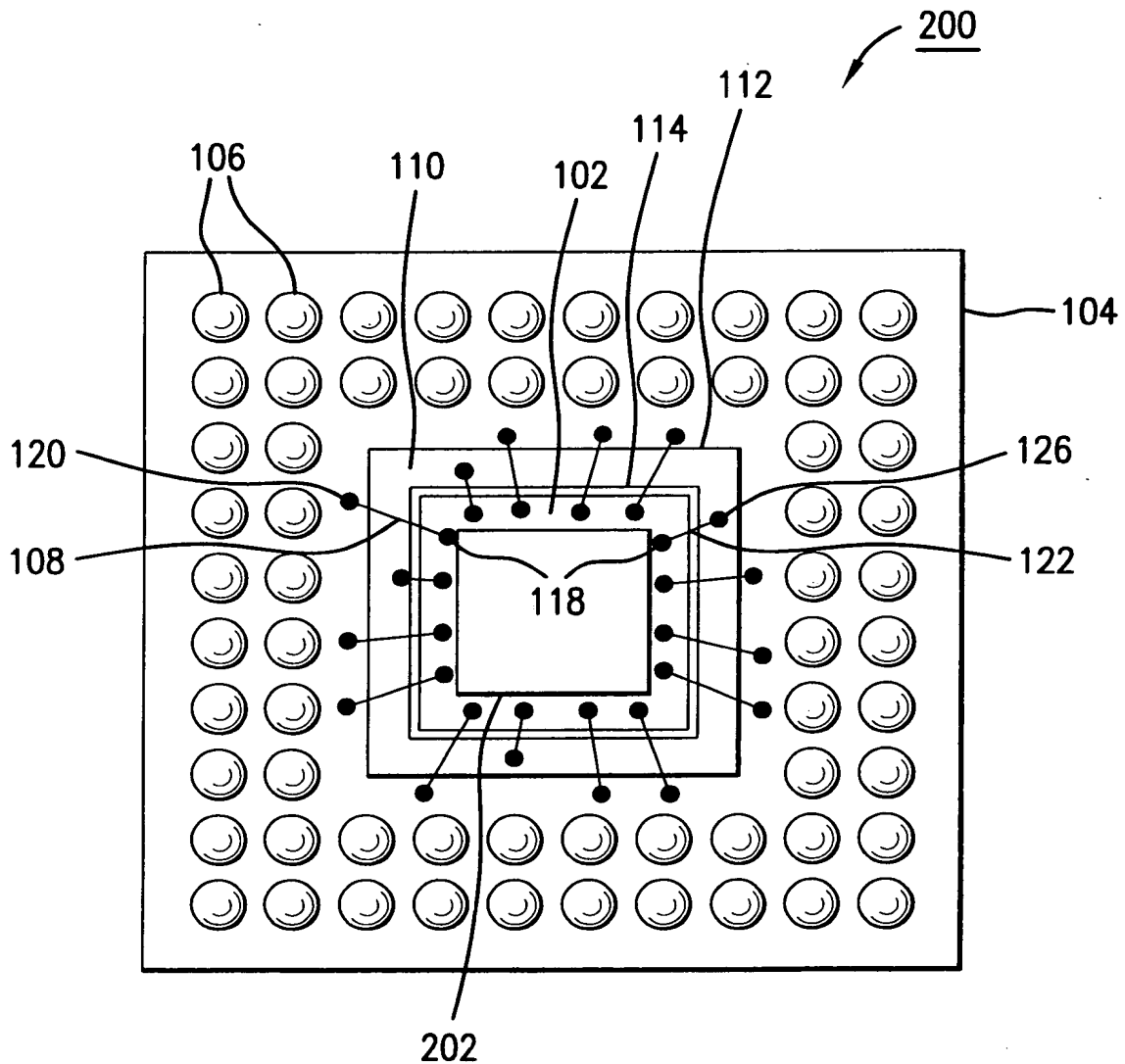


FIG. 2C

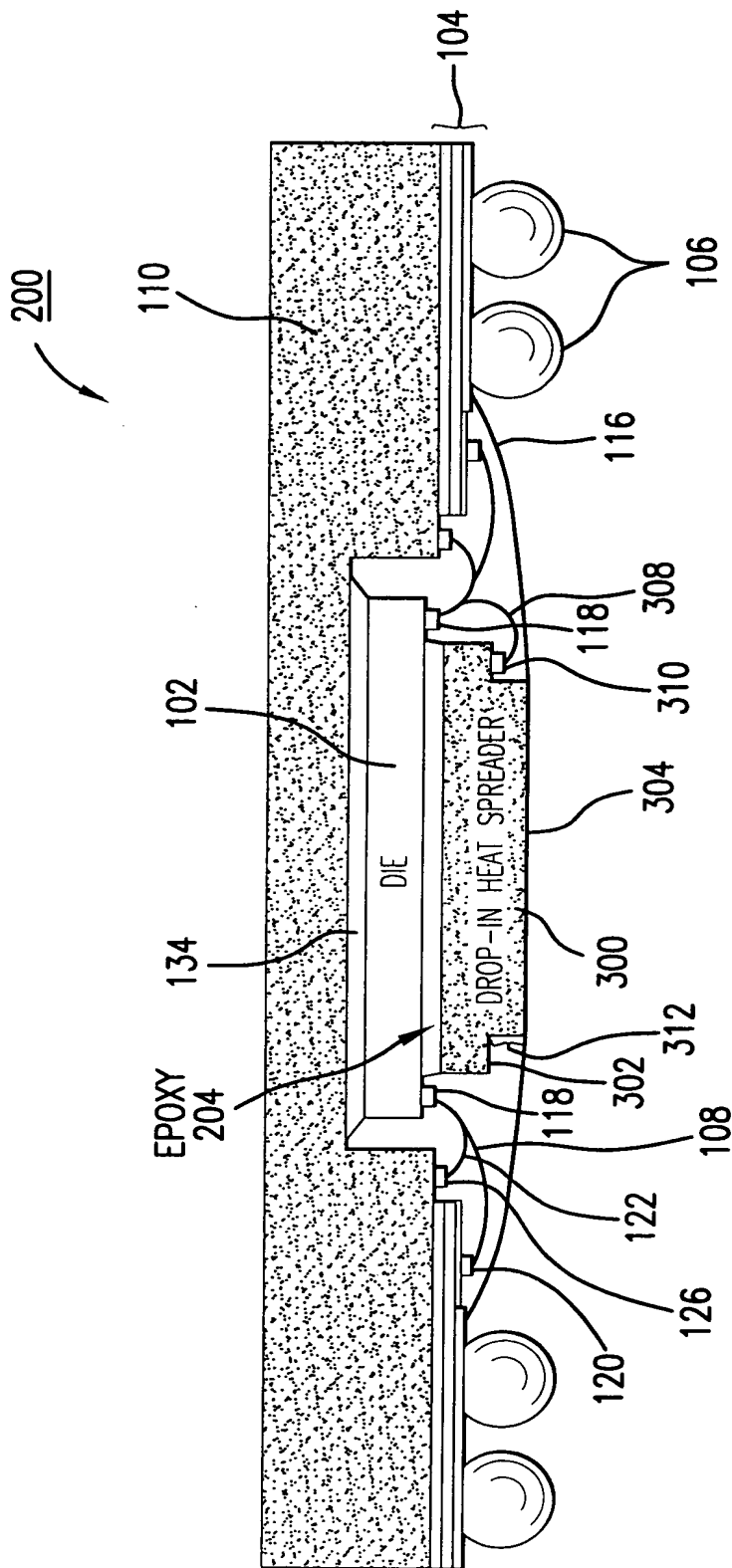


FIG. 3A

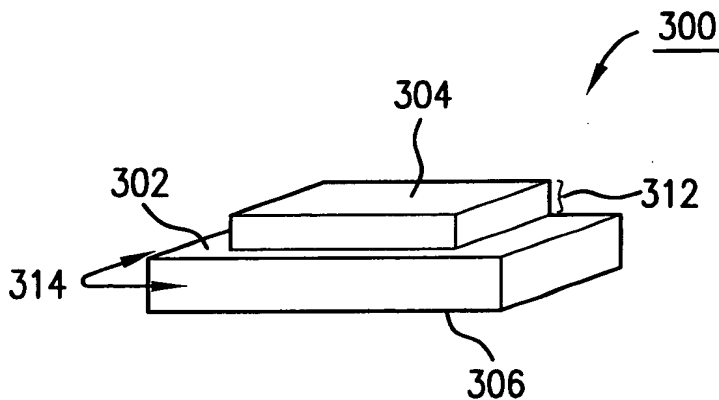


FIG. 3B

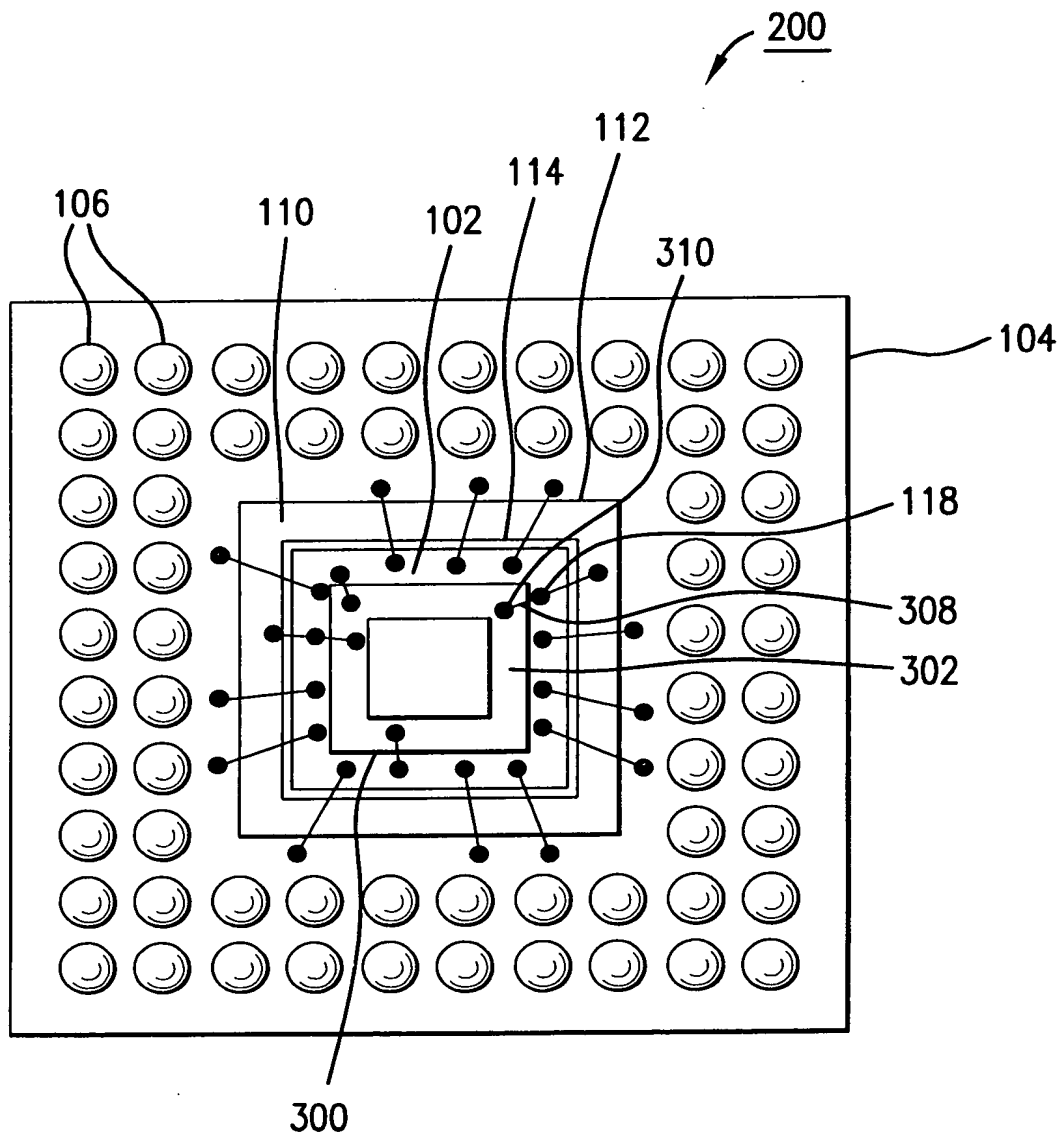
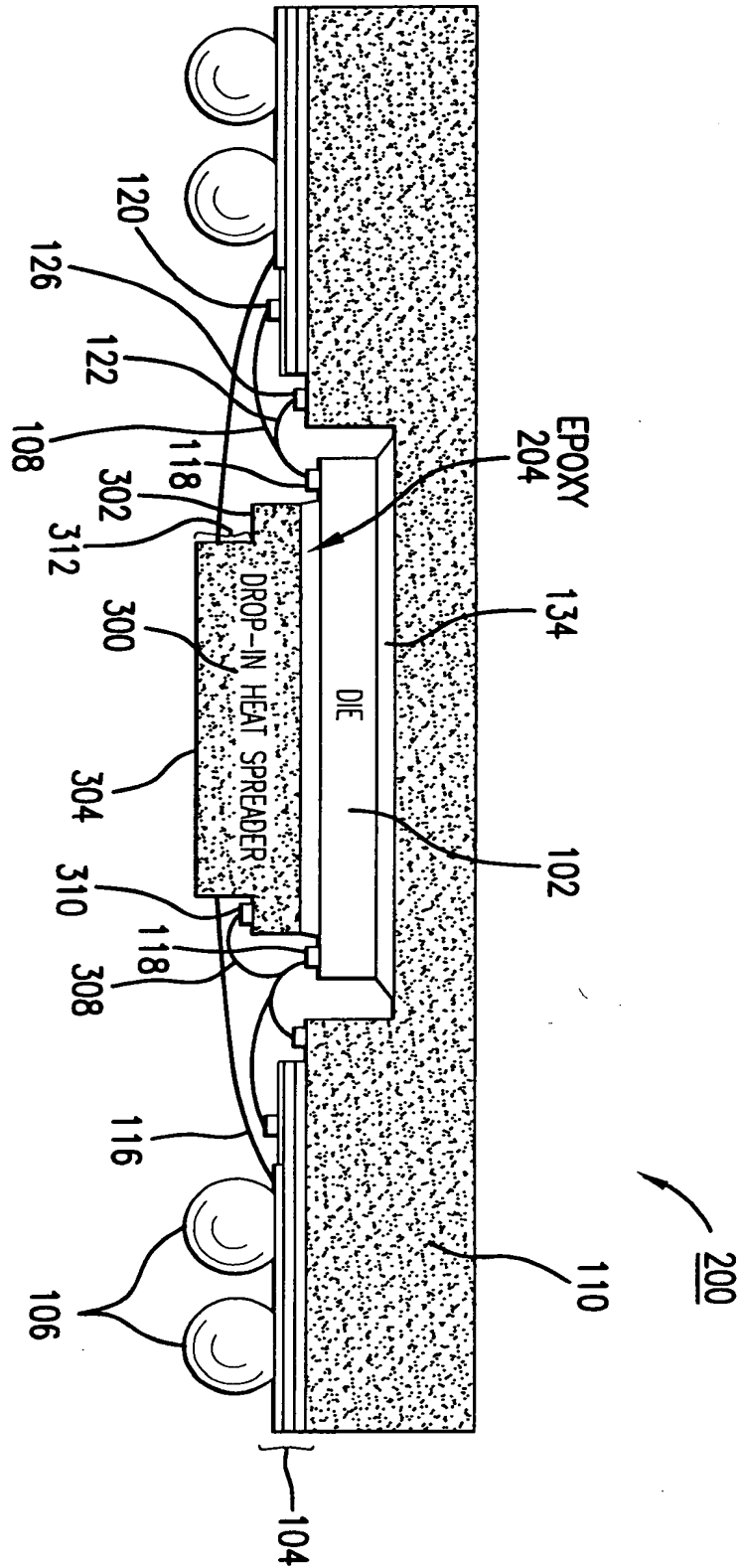


FIG. 3C



FIG. 3D





appl. No. 09/783,034; Filed: February 15, 2001
Int. No. 1875.0210000; Group Art Unit: 2826
inventor(s): Khan *et al.* ; Tel: 202/371-2600
title: Die-Down Ball Grid Array Package With Die-Attached
Heat Spreader and Method For Making the Same

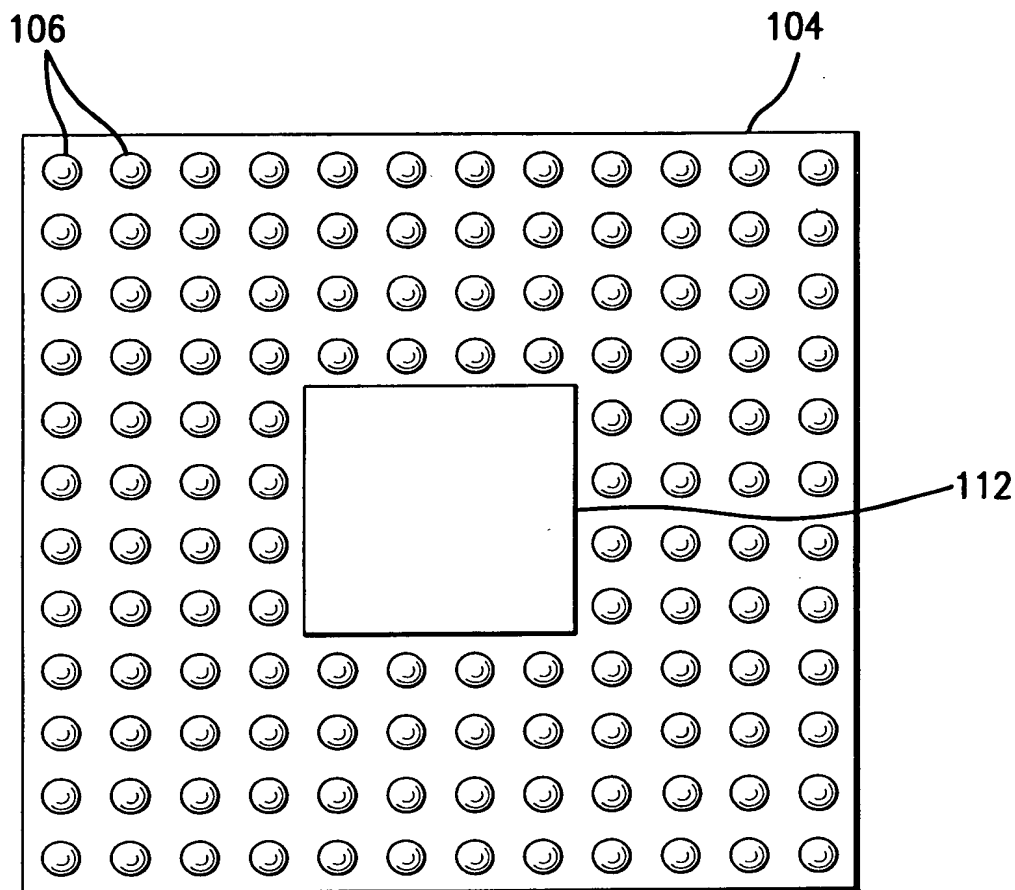


FIG. 4

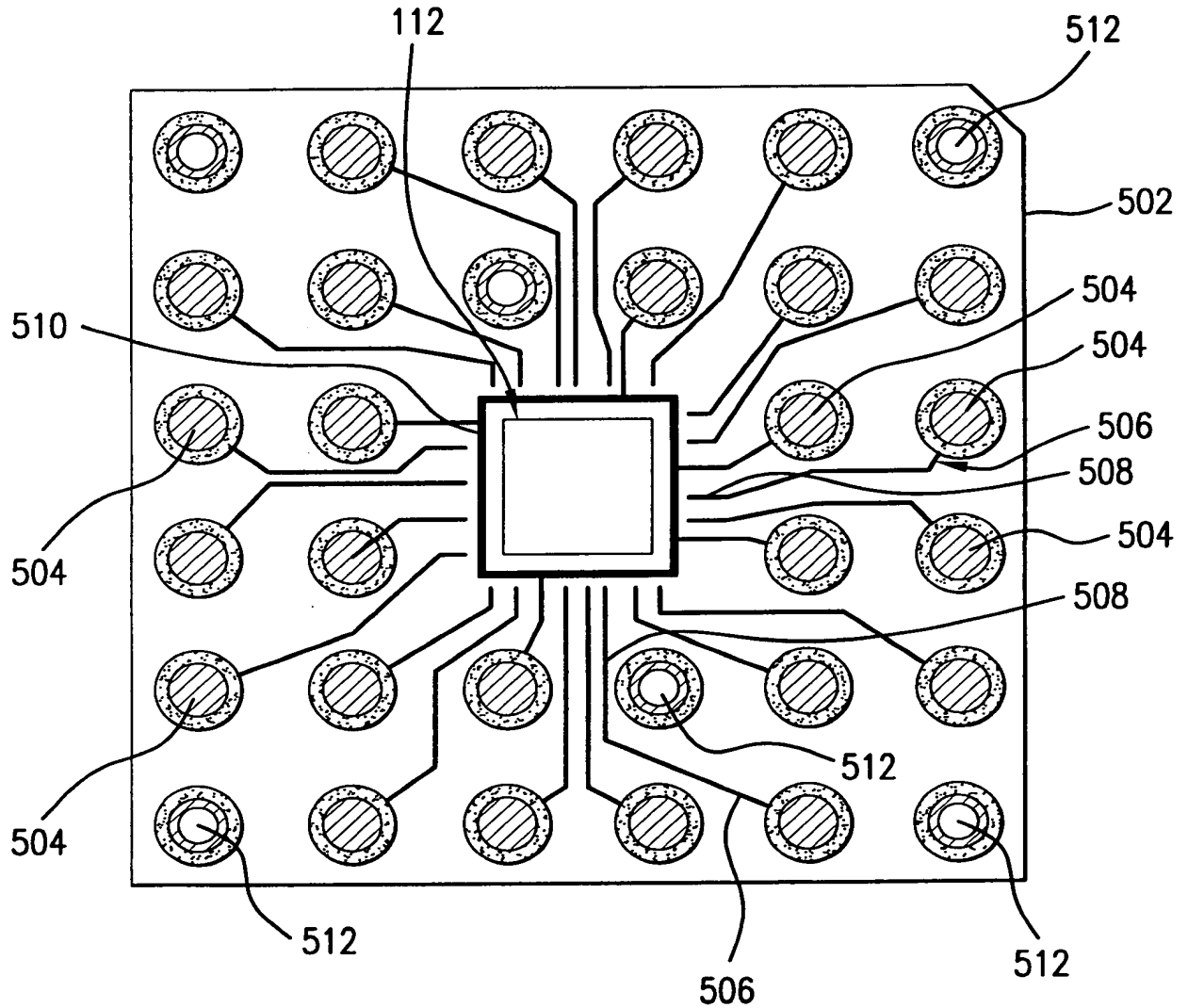


FIG. 5

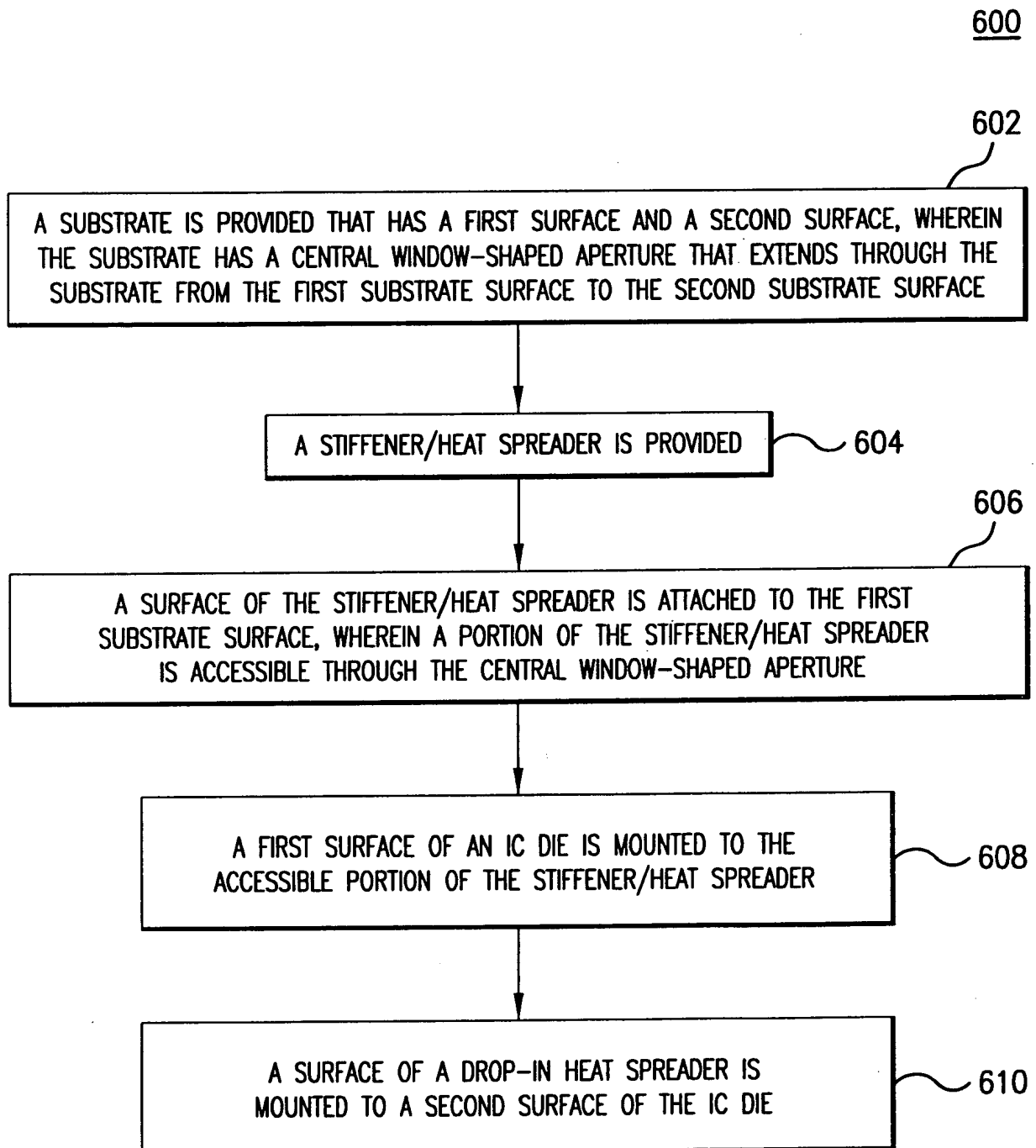


FIG. 6